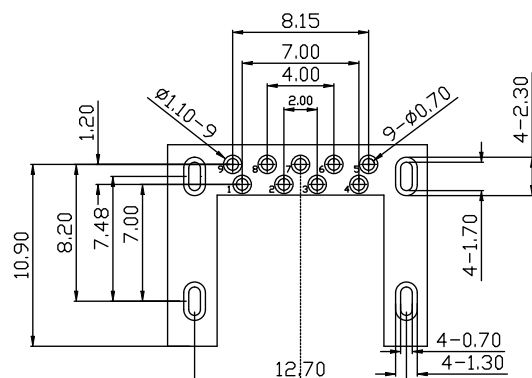
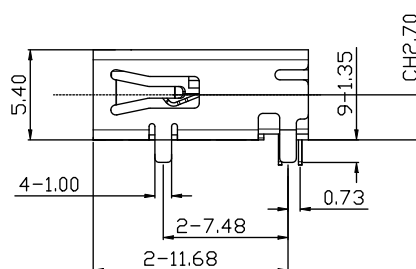
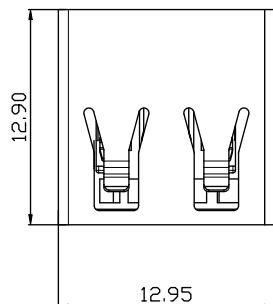
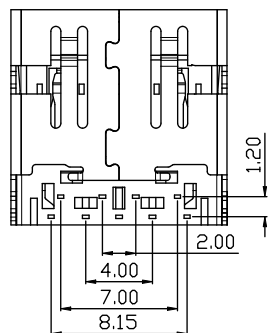
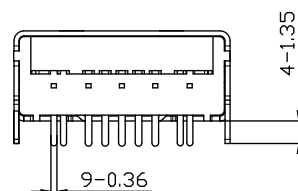
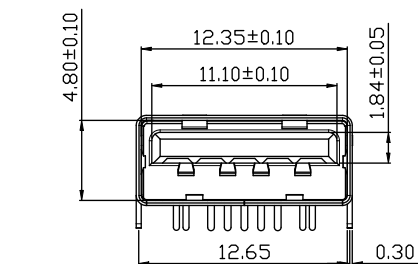




Recommended PCB Layout THK=1.2mm

TOLERANCE=±0.05

NOTE:

1. MATERIAL:

- 1.1 INSULATOR: LCP+30%GF, UL94 V-0.
- 1.2 CONTACT 1~4PIN: 铜合金.
- 1.3 CONTACT 5~9PIN: 铜合金.
- 1.4 SHELL: SUS304 3/4H

2. PLATING:

2.1 CONTACT:

CONTACT AREA: GOLD PLATING.

SOLDER AREA: 100u" Min MATTE TIN PLATING.

UNDER PLATE: 50u" Min NICKEL PLATING.

2.2 SHELL: 50u" Min. NICKEL PLATED OVERALL

3. CHARACTERISTICS:

3.1 ELECTRICAL CHARACTERISTICS:

CONTACT RESISTANCE: 30mΩ MAXIMUM

CONTACT CURRENT RATING: 3A

DIELECTRIC WITHSTANDING VOLTAGE: 500 V R.M.S.

INSULATION RESISTANCE: 1000 MEGOHMS MIN

OPERATING TEMPERATURE: -25°C ~ +85°C

3.2 MECHANICAL:

Before lifespan: insertion force 8-25N;

pull-out force 10-25N.

After lifespan: 6N Min.

4. PART MUST COMPLY ROHS SPECIFICATION

5. SOLDER RESISTANCE TEMPERATURE:

260 ± 5° C FOR 3 MINUTES.

3	SHELL	SUS304-3/4H	50u" Min. NICKEL PLATED OVERALL
2	CONTACT	铜合金	Overall nickel plating 50u" ~ 100u", contact area gold plating 10u", welding leg tin plating 100u"
1	HSG	LCP+30%GF	Black UL94V-0
NO.	PART NAME	MATERIAL	DESCRIPTION



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: USB 3.0 AF 板上DIP H=5.4 CH2.7 无卷边	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW182-USBA09-540B	
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2604281516	
			SHEET NO. 1 OF 1	